

Graphics Code Information

Component

Part Number Decoder

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Part Number Decoder

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1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. DRAM : 4

3. Small Classification

N : gDDR2 SDRAM
W : gDDR3 SDRAM
J : GDDR3 SDRAM
G : GDDR5 SDRAM

4~5. Density, Refresh

51 : 512M, 8K/64ms
52 : 512M, 8K/32ms
10 : 1G, 8K/32ms
1G : 1G, 8K/64ms
2G : 2G, 8K/64ms
4G : 4G, 8K/64ms

6~7. Organization

16 : x16 32 : x32

8. Bank

3 : 4Banks
4 : 8Banks

9. Interface, VDD, VDDQ

Q : SSTL_2, 1.8V, 1.8V
5 : SSTL_2, 1.8V, 1.8V, LP
6 : SSTL_15, 1.5V, 1.5V
F : POD_15, 1.5V, 1.5V
K : POD_18, 1.8V, 1.8V

10. Generation

M : M-die A : A-die
B : B-die C : C-die
D : D-die E : E-die
F : F-die G : G-die
H : H-die I : I-die
Q : Q-die Z : Z-die

11. "—"

12. Package

- gDDR2

H : 84FBGA (Halogen Free & Lead Free)
B : 84FBGA (Halogen Free & Lead Free & Flip Chip)

- gDDR3

E : 100FBGA (Halogen Free & Lead Free)
H : 96FBGA (Halogen Free & Lead Free)
B : 96FBGA (Flip-Chip)

- GDDR3

B : 136FBGA (Lead Free)
H : 136FBGA (Halogen Free & Lead Free)

- GDDR5

H : 170FBGA (Halogen Free & Lead Free)

13. Temp, Power(VDD)

C : Commercial Normal
J : Commercial High
L : Commercial Low

14~15. Speed (Wafer/Chip Biz/BGD : 00)

1A : 0.935ns (2133Mbps)	28 : 0.28ns (7000Mbps)
11 : 1.07ns (1866Mbps)	03 : 0.33ns (6000Mbps)
12 : 1.25ns (1600Mbps)	04 : 0.40ns (5000Mbps)
14 : 1.4ns (1400Mbps)	05 : 0.50ns (4000Mbps)
15 : 1.5ns (1333Mbps)	5C : 0.56ns (3600Mbps)
16 : 1.6ns (1200Mbps)	06 : 0.62ns (3200Mbps)
18 : 1.8ns (1100Mbps)	6A : 0.66ns (3000Mbps)
19 : 1.875ns (1066Mbps)	07 : 0.71ns (2800Mbps)
20 : 2.0ns (1000Mbps)	7A : 0.77ns (2600Mbps)
22 : 2.2ns (900Mbps)	08 : 0.8ns (2400Mbps)
25 : 2.5ns (800Mbps)	09 : 0.9ns (2200Mbps)